

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claims 4-5 and CANCEL claims 9-10 in accordance with the following:

1. (Previously Presented) A device for fabricating a lead frame by press forming, comprising:

a die having a flat face, on which a lead frame to be fabricated by press forming is to be placed, and a first concavity, which is dented relative to the flat face, the die possessing a fabricating face extending from the bottom of the first concavity to the flat face through a slant, which is interposed between the bottom of the first concavity and the flat face, the fabricating face contributing to the fabrication of a lead frame by press forming; and

a punch having punching faces formed so as to be opposite to the fabricating faces of the die for the fabrication of the lead frame by press forming;

wherein at least one of the die and the punch are movable so as to hold the lead frame between the fabricating face of the die and the punching face of the punch for the fabrication of the lead frame by press forming; and

wherein the bottom of the first concavity of the die has a second concavity, which is dented relative to the bottom, so as not to come into contact with the lead frame during the press forming thereof, and the punch has a front end opposite to the bottom of the first concavity of the die, the front end being formed so as to have a portion partially spreading over the second concavity.

2. (Previously Presented) The device of claim 1, wherein the lead frame to be fabricated by bending has a die-pad, on which a semiconductor chip is to be mounted, and support bars for supporting the die-pad, and wherein the first concavity of the die is formed such that the die-pad of the lead frame is located over the first concavity and the respective support bars of the lead frame straddle the first concavity when the lead frame is placed on the flat face of the die.

3. (Original) The device of claim 1, wherein the punch is movable relative to the die.

4. (Currently Amended) A method for fabricating a lead frame by press forming, comprising:

fabricating the lead frame by press forming between a die and a punch; wherein the device used to fabricate includes:

a wherein the die having has a flat face, on which a the lead frame to be fabricated by press forming is to be placed, and a first concavity, which is dented relative to the flat face, the die possessing a fabricating face extending from the bottom of the first concavity to the flat face through a slant, which is interposed between the bottom of the first concavity and the flat face, the fabricating face contributing to the fabrication of a lead frame by press forming; and

a wherein the punch having has punching faces formed so as to be opposite to the fabricating faces of the die for the fabrication of the lead frame by press forming;

wherein at least one of the die and the punch are movable so as to hold the lead frame between the fabricating face of the die and the punching face of the punch for the fabrication of the lead frame by press forming; and

wherein ~~the die has a first concavity,~~ the bottom of which the first concavity has a second concavity, which is dented relative to the bottom, so as not to come into contact with the lead frame during the press forming thereof, and the punch has a front end opposite to the bottom of the first concavity of the die, the front end being formed so as to have a portion partially spreading over the second concavity.

5. (Currently Amended) The method of claim 4, ~~which wherein fabricates a lead frame having a die-pad by press forming~~ is fabricated, and on which a semiconductor chip is to be mounted, and support bars for supporting the die-pad, and wherein the first concavity of the die is formed such that the die-pad of the lead frame is located over the first concavity and the respective support bars of the lead frame straddle the first concavity when the lead frame is placed on the flat face of the die.

6. (Original) The method of claim 4, wherein the punch is moved relative to the die.

7-10. (Cancelled)